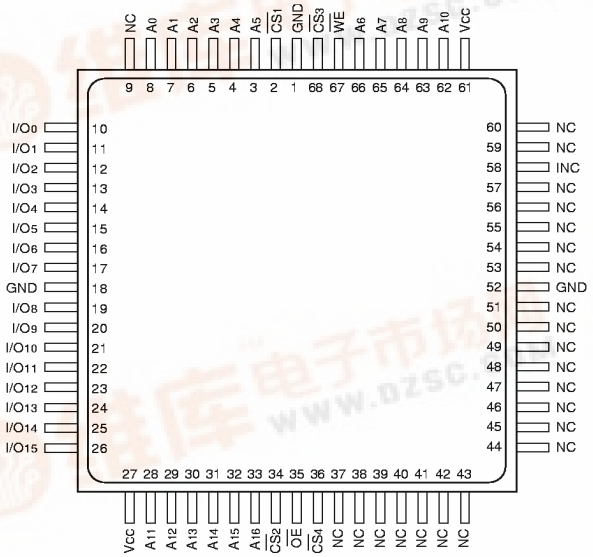
512Kx16 CMOS EEPROM MODULE

FEATURES

- Access Time of 120, 150, 200ns
- Packaging:
  - 68 lead, 40mm Hermetic CQFP (Package 501)
- Organized as 4 banks of 128Kx16
- Write Endurance 10,000 Cycles
- Data Retention Ten Years Minimum
- Military Temperature Range
- Low Power CMOS
- Automatic Page Write Operation
- Page Write Cycle Time: 10ms Max
- Data Polling for End of Write Detection
- Hardware and Software Data Protection
- TTL Compatible Inputs and Outputs
- 5 Volt Power Supply
- 8 Built-in Decoupling Caps and Multiple Ground Pins for Low Noise Operation
- Weight - 20 grams typical

FIG. 1 PIN CONFIGURATION

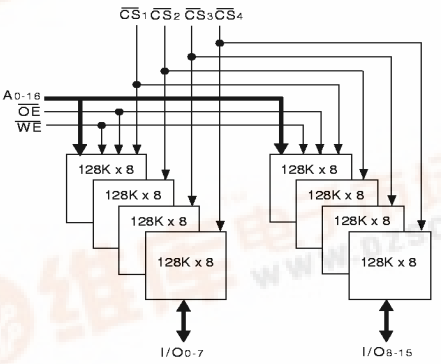
TOP VIEW



PIN DESCRIPTION

I/O_{0-15}	Data Inputs/Outputs
A_{0-16}	Address Inputs
$\overline{WE}$	Write Enable
$\overline{CS}_{1-4}$	Chip Selects
$\overline{OE}$	Output Enable
V_{CC}	Power Supply
GND	Ground
NC	Not Connected

BLOCK DIAGRAM



NOTE:
$\overline{CS}_{1-4}$ are used as bank selects. During reads, only one $\overline{CS}$x can be active at one time.

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol		Unit
Operating Temperature	T_A	-55 to +125	°C
Storage Temperature	T_{STG}	-65 to +150	°C
Signal Voltage Relative to GND	V_G	-0.6 to +6.25	V
Voltage on $\overline{OE}$ and A9		-0.6 to +13.5	V

NOTE:
Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Max	Unit
Supply Voltage	V_{CC}	4.5	5.5	V
Input High Voltage	V_{IH}	2.0	Vcc + 0.3	V
Input Low Voltage	V_{IL}	-0.3	+0.8	V
Operating Temp. (Mil.)	T_A	-55	+125	°C

TRUTH TABLE

$\overline{CS}$	$\overline{OE}$	$\overline{WE}$	Mode	Data I/O
H	X	X	Standby	High Z
L	L	H	Read	Data Out
L	H	L	Write	Data In
X	H	X	Out Disable	High Z/Data Out
X	X	H	Write	
X	L	X	Inhibit	

CAPACITANCE

(T_A = +25°C)

Parameter	Symbol	Conditions	Max	Unit
$\overline{OE}$ capacitance	C_{OE}	V_{IN} = 0 V, f = 1.0 MHz	50	pF
$\overline{WE}$ capacitance	C_{WE}	V_{IN} = 0 V, f = 1.0 MHz	50	pF
$\overline{CS}_{1-4}$ capacitance	C_{CS}	V_{IN} = 0 V, f = 1.0 MHz	25	pF
Data I/O capacitance	$C_{I/O}$	$V_{I/O}$ = 0 V, f = 1.0 MHz	40	pF
Address input capacitance	C_{AD}	V_{IN} = 0 V, f = 1.0 MHz	70	pF

This parameter is guaranteed by design but not tested.

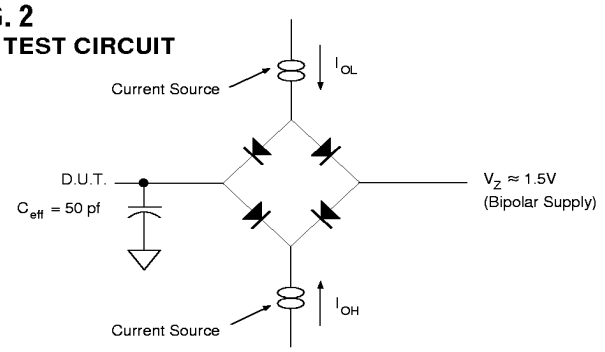
DC CHARACTERISTICS

(V_{CC} = 5.0V, GND = 0V, T_A = -55°C to +125°C)

Parameter	Symbol	Conditions	Min	Max	Unit
Input Leakage Current	I_{LI}	V_{CC} = 5.5, V_{IN} = GND to V_{CC}		10	µA
Output Leakage Current	I_{LO}	$\overline{CS}$ = V_{IH}, $\overline{OE}$ = V_{IH}, V_{OUT} = GND to V_{CC}		10	µA
Operating Supply Current (x16)	I_{CCx16}	$\overline{CS}_1$ = V_{IL}, $\overline{OE}$ = $\overline{CS}_{2-4}$ = V_{IH}, f = 5MHz, V_{CC} = 5.5		160	mA
Chip Erase Current	I_{CC1}	$\overline{CS}$ = V_{IL}, $\overline{OE}$ = V_{IH}, f = 5MHz, V_{CC} = 5.5		250	mA
Standby Current (CMOS)	I_{SB}	$\overline{CS}$ = V_{IH}, $\overline{OE}$ = V_{IH}, f = 5MHz, V_{CC} = 5.5		5	mA
Output Low Voltage	V_{OL}	I_{OL} = 2.1mA, V_{CC} = 4.5V		0.45	V
Output High Voltage	V_{OH}	I_{OH} = -400µA, V_{CC} = 4.5V	2.4		V

NOTE: DC test conditions: V_{IH} = V_{CC} -0.3V, V_{IL} = 0.3V

FIG. 2
AC TEST CIRCUIT



AC TEST CONDITIONS

Parameter	Typ	Unit
Input Pulse Levels	V_{IL} = 0, V_{IH} = 3.0	V
Input Rise and Fall	5	ns
Input and Output Reference Level	1.5	V
Output Timing Reference Level	1.5	V

NOTES:
V_Z is programmable from -2V to +7V.
I_{OL} & I_{OH} programmable from 0 to 16mA.
Tester Impedance Z_0 = 75 Ω.
V_Z is typically the midpoint of V_{OH} and V_{OL}.
I_{OL} & I_{OH} are adjusted to simulate a typical resistive load circuit.
ATE tester includes jig capacitance.

WRITE

A write cycle is initiated when $\overline{OE}$ is high and a low pulse is on $\overline{WE}$ or $\overline{CS}$ with $\overline{CS}$ or $\overline{WE}$ low. The address is latched on the falling edge of $\overline{CS}$ or $\overline{WE}$ whichever occurs last. The data is latched by the rising edge of $\overline{CS}$ or $\overline{WE}$, whichever occurs first. A word write operation will automatically continue to completion.

WRITE CYCLE TIMING

Figures 3 and 4 show the write cycle timing relationships. A write cycle begins with address application, write enable and chip select. Chip select is accomplished by placing the $\overline{CS}$ line low. Write enable consists of setting the $\overline{WE}$ line low. The write cycle begins when the last of either $\overline{CS}$ or $\overline{WE}$ goes low.

The $\overline{WE}$ line transition from high to low also initiates an internal 150 µsec delay timer to permit page mode operation. Each subsequent $\overline{WE}$ transition from high to low that occurs before the completion of the 150 µsec time out will restart the timer from zero. The operation of the timer is the same as a retriggerable one-shot.

AC WRITE CHARACTERISTICS

(V_{CC} = 5.0V, GND = 0V, T_A = -55°C to +125°C)

Write Cycle Parameter	Symbol	Min	Max	Unit
Write Cycle Time, TYP = 6ms	t_{WC}		10	ms
Address Set-up Time	t_{AS}	10		ns
Write Pulse Width ($\overline{WE}$ or $\overline{CS}$)	t_{WP}	120		ns
Chip Select Set-up Time	t_{CS}	0		ns
Address Hold Time	t_{AH}	100		ns
Data Hold Time	t_{DH}	10		ns
Chip Select Hold Time	t_{CSH}	0		ns
Data Set-up Time	t_{DS}	100		ns
Output Enable Set-up Time	t_{OES}	10		ns
Output Enable Hold Time	t_{OEH}	10		ns
Write Pulse Width High	t_{WPH}	50		ns

FIG. 3
WRITE WAVEFORM
WE CONTROLLED

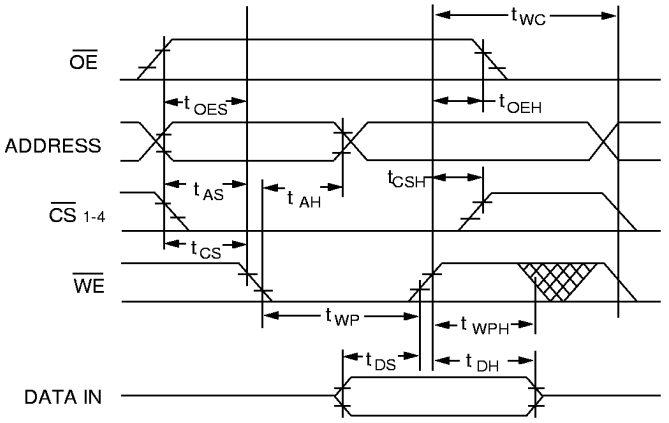
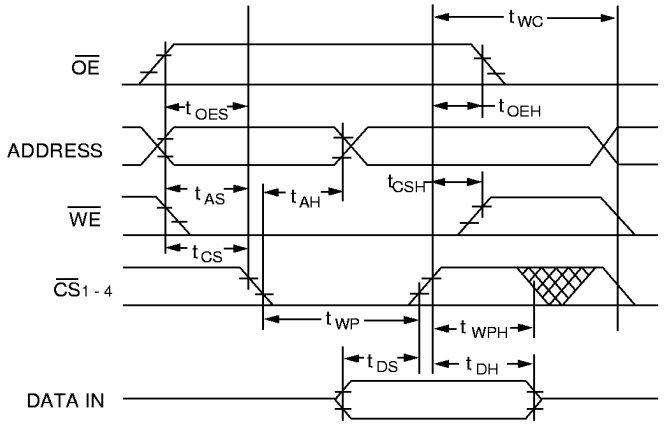


FIG. 4
WRITE WAVEFORM
CS CONTROLLED



READ

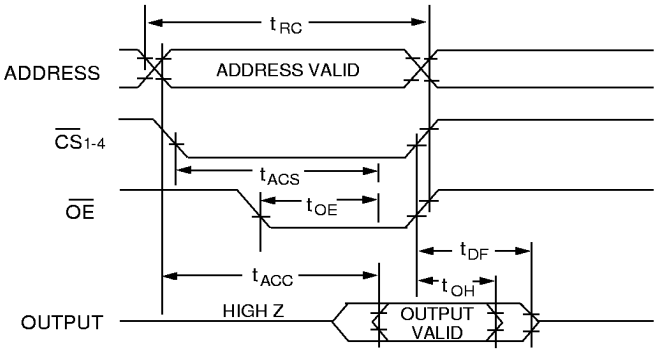
The module stores data at the memory location determined by the address pins. When $\overline{CS}$ and $\overline{OE}$ are low and $\overline{WE}$ is high, this data is present on the outputs. When $\overline{CS}$ and $\overline{OE}$ are high, the outputs are in a high impedance state. This two line control prevents bus contention.

AC READ CHARACTERISTICS

(V_{CC} = 5.0V, GND = 0V, T_A = -55°C to +125°C)

Read Cycle Parameter	Symbol	-120		-150		-200		Unit
		Min	Max	Min	Max	Min	Max	
Read Cycle Time	t_{RC}	120		150		200		ns
Address Access Time	t_{ACC}		120		150		200	ns
Chip Select Access Time	t_{ACS}		120		150		200	ns
Output Hold from Add. Change, $\overline{OE}$ or $\overline{CS}$	t_{OH}	0		0		0		ns
Output Enable to Output Valid	t_{OE}	0	50	0	55	0	55	ns
Chip Select or $\overline{OE}$ to High Z Output	t_{DF}		50		70		70	ns

FIG. 5
READ WAVEFORM



NOTES:
$\overline{OE}$ may be delayed up to t_{ACS} - t_{OE} after the falling edge of $\overline{CS}$ without impact on t_{OE} or by t_{ACC} - t_{OE} after an address change without impact on t_{ACC}.
$\overline{CS}_{1-4}$ are used as bank selects.
During reads, only one $\overline{CS}$x can be active at one time.

DATA POLLING

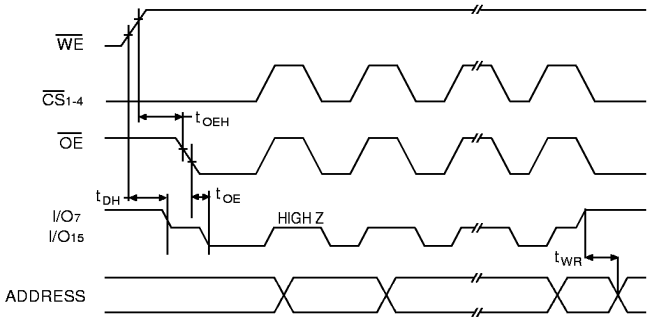
The module offers a data polling feature which allows a faster method of writing to the device. Figure 6 shows the timing diagram for this function. During a word or page write cycle, an attempted read of the last word written will result in the complement of the written data on I/O_7 and I/O_{15}. Once the write cycle has been completed, true data is valid on all outputs and the next cycle may begin. Data polling may begin at any time during the write cycle.

DATA POLLING CHARACTERISTICS

(V_{CC} = 5.0V, GND = 0V, T_A = -55°C to +125°C)

Parameter	Symbol	Min	Max	Unit
Data Hold Time	t_{DH}	10		ns
$\overline{OE}$ Hold Time	t_{OEH}	10		ns
$\overline{OE}$ To Output Valid	t_{OE}		55	ns
Write Recovery Time	t_{WR}	0		ns

FIG. 6
DATA POLLING WAVEFORM



PAGE WRITE OPERATION

The module has a page write operation that allows one to 128 words of data to be written into the device and consecutively loads during the internal programming period. Successive words may be loaded in the same manner after the first data word has been loaded. An internal timer begins a time out operation at each write cycle. If another write cycle is completed within 150µs or less, a new time out period begins. Each write cycle restarts the delay period. The write cycles can be continued as long as the interval is less than the time out period.

The usual procedure is to increment the least significant address lines from A_0 through A_6 at each write cycle. In this manner a page of up to 128 words can be loaded in to the EEPROM in a burst mode before beginning the relatively long interval programming cycle.

After the 150µs time out is completed, the EEPROM begins an internal write cycle. During this cycle the entire page of words will be written at the same time. The internal programming cycle is the same regardless of the number of words accessed.

PAGE WRITE CHARACTERISTICS

(V_{CC} = 5.0V, GND = 0V, T_A = -55°C to +125°C)

Page Mode Write Characteristics	Symbol			Unit
Parameter		**Min**	**Max**	
Write Cycle Time, TYP = 6ms	t_{WC}		10	ms
Address Set-up Time	t_{AS}	0		ns
Address Hold Time (1)	t_{AH}	50		ns
Data Set-up Time	t_{DS}	50		ns
Data Hold Time	t_{DH}	0		ns
Write Pulse Width	t_{WP}	100		ns
Word Load Cycle Time	t_{BLC}		150	µs
Write Pulse Width High	t_{WPH}	50		ns

1. Page address must remain valid for duration of write cycle.

FIG. 7
PAGE MODE
WRITE WAVEFORM

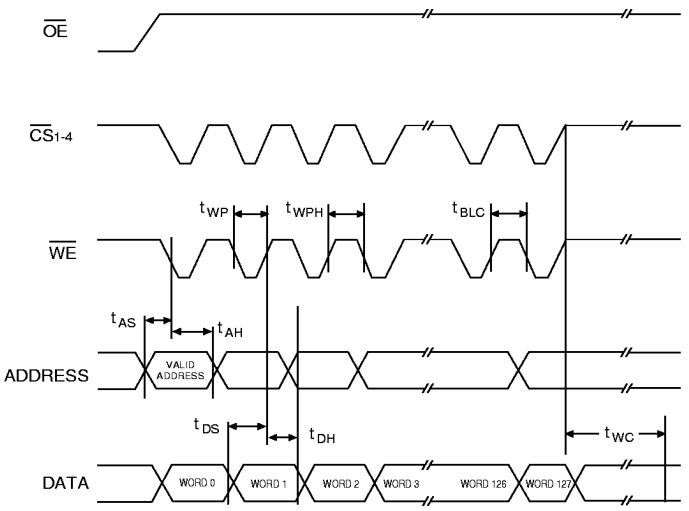
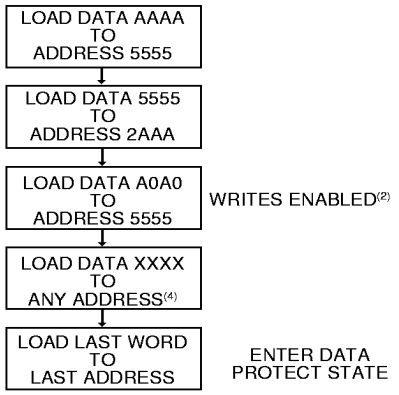
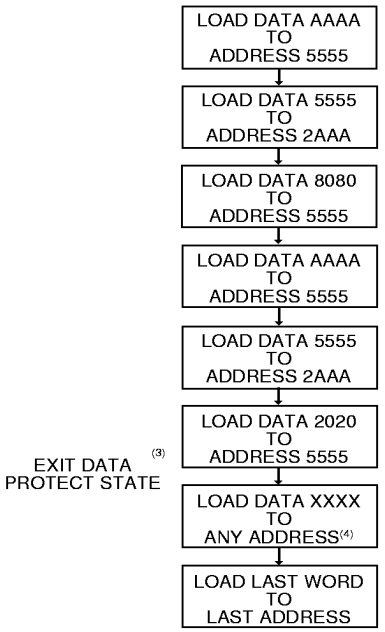


FIG. 8
SOFTWARE DATA PROTECTION ENABLE ALGORITHM(1)



NOTES:
1. Data Format: I/O_{15-0} (Hex);
   Address Format: A_{16-0} (Hex).
2. Write Protect state will be activated at end of write even if no other data is loaded.
3. Write Protect state will be deactivated at end of write period even if no other data is loaded.
4. 1 to 128 words of data may be loaded.

FIG. 9
SOFTWARE DATA PROTECTION DISABLE ALGORITHM(1)



NOTES:
1. Data Format: I/O_{15-0} (Hex);
   Address Format: A_{16-0} (Hex).
2. Write Protect state will be activated at end of write even if no other data is loaded.
3. Write Protect state will be deactivated at end of write period even if no other data is loaded.
4. 1 to 128 words of data may be loaded.

SOFTWARE DATA PROTECTION

A software write protection feature may be enabled or disabled by the user. When shipped by White Microelectronics, the module has the feature disabled. Write access to the device is unrestricted.

To enable software write protection, the user writes three access code words to three special internal locations. Once write protection has been enabled, each write to the EEPROM must use the same three-word write sequence to permit writing. After setting software data protection, any attempt to write to the device without the three-word command sequence will start the internal write timers. No data will be written to the device, however, for the duration of t_{WC}. The write protection feature can be disabled by a six-word write sequence of specific data to specific locations. Power transitions will not reset the software write protection.

Each 128K-word block of the EEPROM has independent write protection. One or more blocks may be enabled and the rest disabled in any combination. The software write protection guards against inadvertent writes during power transitions, or unauthorized modification using a PROM programmer.

HARDWARE DATA PROTECTION

These features protect against inadvertent writes to the module. These are included to improve reliability during normal operation:

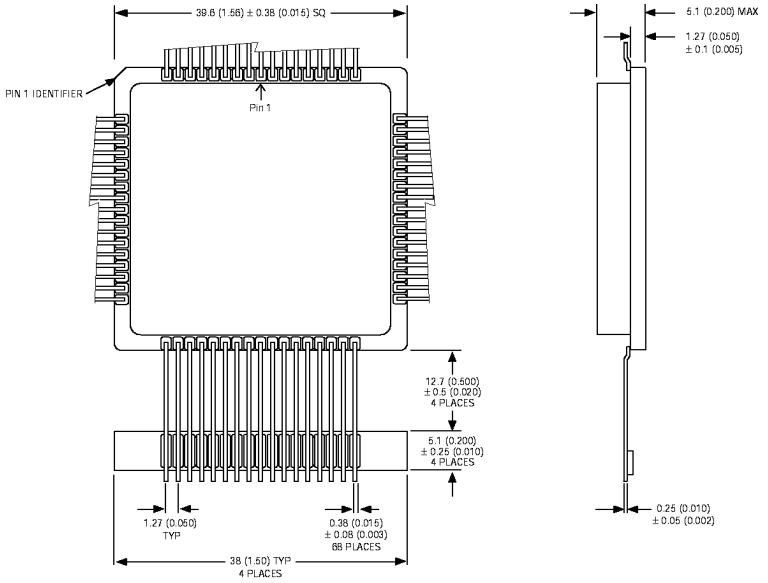
a) Vcc power on delay
As V_{CC} climbs past 3.8V typical the device will wait 5 msec typical before allowing write cycles.

b) Vcc sense
While below 3.8V typical write cycles are inhibited.

c) Write inhibiting
Holding $\overline{OE}$ low and either $\overline{CS}$ or $\overline{WE}$ high inhibits write cycles.

d) Noise filter
Pulses of <8ns (typ) on $\overline{WE}$ or $\overline{CS}$ will not initiate a write cycle.

PACKAGE 501: 68 LEAD, CERAMIC QUAD FLAT PACK, CQFP (G4)



ALL LINEAR DIMENSIONS ARE MILLIMETERS AND PARENTHETICALLY IN INCHES

ORDERING INFORMATION

W E 512K16 - XXX G4 X X

LEAD FINISH:
- Blank = Gold plated leads
- A = Solder dip leads

PROCESSING:

Q = MIL-STD-883 Compliant	
M = Military Screened	-55°C to +125°C
I = Industrial	-40°C to +85°C
C = Commercial	0°C to +70°C

PACKAGE:
- G4 = 40mm Ceramic Quad Flat Pack, CQFP (Package 501)

ACCESS TIME (ns)

ORGANIZATION, 4 banks of 128Kx16

EEPROM

WHITE MICROELECTRONICS